

INTERNATIONAL STANDARD



**Explosive atmospheres –
Part 11: Equipment protection by intrinsic safety "i"**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

EXPLOSIVE ATMOSPHERES –**Part 11: Equipment protection by intrinsic safety "i"****FOREWORD**

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IEC 60079-11 has been prepared by subcommittee 31G: Intrinsically safe apparatus, of IEC technical committee 31: Equipment for explosive atmospheres. It is an International Standard.

This seventh edition cancels and replaces the sixth edition published in 2011. This edition constitutes a technical revision.

The significance of changes between IEC 60079-11, Edition 7 (2023) and IEC 60079-11, Edition 6 (2011 + Corrigendum 1 (2012)) are as listed below:

Explanation of the significance of changes	Clause	Type		
		Minor and editorial changes	Extension	Major technical changes
A significant number of editorial changes including re-structuring of sections. These are too numerous to list in this table.	All	X		
Protection of catalytic elements for Group IIC or Group IIB + H ₂ excluded from the scope of the standard.	1 7.14.2			C2
Extension, with requirements, of ambient pressure down to 60 kPa.	1 6.5.6.1		B1	
Modification to Table 1 showing Clause 14 of IEC 60079-0 as 'Applies'. This does not affect the technical requirements.	1	X		
Definitions removed as they are now in IEC 60079-0. (References are from Ed.6) 3.2 coating 3.3 conformal coating 3.7.1 countable fault 3.7.3 non-countable fault 3.18 recurring peak voltage 3.20 encapsulation 3.21 casting 3.23 galvanic isolation	3	X		
Definitions removed as they are no longer considered necessary. (References are from Ed.6) 3.7.2 fault 3.10.3 Infallible separation	3	X		
Diode safety barriers no longer refers to devices that provide galvanic isolation.	3.1.7 7.7.5		X	
Intrinsic safety parameters and U_m can have brief transients above the stated values, and these do not need to be taken into account.	3.1.12 7.7.3	X		
New definition – spark test apparatus.	3.1.14	X		
New definition – electrochemical capacitor.	3.1.15		X	
New definition – transient rating.	3.1.16.1		X	
New definition – transient energy (previously let-through energy).	3.1.16.2	X		
New definition – non-hazardous area accessory.	3.1.17	X		
Clarification that it is not a requirement of this standard that conformance to industrial standards be verified.	5.1	X		
Clarification of conditions for the assessment added.	5.2.1	X		
Clarification relating to the application of service temperatures.	5.2.1 g)			C1
Statements that Level of Protection "ia" and "ib" requirements are always sufficient for Level of Protection "ic".	5.2.2		X	

Explanation of the significance of changes	Clause	Type		
		Minor and editorial changes	Extension	Major technical changes
For Level of Protection "ic", faults are only considered for spark ignition assessment and the determination of U_0 , I_0 , L_i , C_i and L_i/R_i . A short circuit fault, and subsequent component faults arising, are now termed non-countable faults.	5.2.4 6.5.4.3 6.5.4.4 6.5.4.5			C3
For Level of Protection "ic", the types of components on which intrinsic safety depends are limited.	5.2.4		X	
Clarification of the requirements for non-shock hazard equipment or systems (for example SELV / PELV) for declaration of U_m .	5.2.5 12.1 c)	A1		
Clarification of where spark ignition assessment should and should not be applied.	5.3.1	X		
Clarification that spark ignition assessment may be performed on a representative circuit.	5.3.1 9.1.1	X		
Spark ignition assessment at normal ambient is suitable for service temperatures between -60 °C and 100 °C.	5.3.1		X	
Spark ignition testing of mains apparatus is at U_m rather than 110 % of the mains nominal voltage.	5.3.4.2 d)	X		
Annex G added as option for spark ignition assessment.	5.3.4.1 5.3.4.2 9.2.6 c) Annex G		X	
Clarification of the requirements for circuits with controlled semiconductor limitation, including need to consider both steady state and transient spark ignition compliance for circuits with controlled semiconductor limitation.	5.3.6 Annex D			C4
The exclusion of the IEC 60079-0 10 % safety margin on voltage for thermal ignition assessment extended to Groups I and II.	5.4.1		X	
The 1,3 W limit for T4 for tracks on a printed circuit board now only applies to 40 °C ambient.	5.4.1			C5
The 5K and 10K margin required for temperature tests from IEC 60079-0 now apply for Level of Protection "ic".	5.4.2			C6
Corrected the formula for thermal assessment of wires.	5.4.3			C7
Clarified that only circuit board tracks exposed to the explosive atmosphere require temperature classification.	5.4.4	X		
Added a note identifying examples of available data for determining temperature rise in PCB tracks (From IPC-2221 and IPC-2152).	5.4.4	X		
Clarified which dimensions can be reduced by manufacturer's tolerance (track width, board thickness, and conductor thickness).	5.4.4	X		
Clarified the use of Table 4 by introducing reduction factors for board thickness, number of layers, copper thickness, track under component, and ambient temperature.	5.4.4		X	
Added allowance for linear interpolation of allowed current, track width, track thickness, ambient temperature, and board thickness.	5.4.4		X	
Extrapolation of Table 4 is prohibited.	5.4.4			C1
Reduced the default board thickness for application of Table 4 from 1,6 mm to 1,55 mm to reflect industry standard.	5.4.4		X	

Explanation of the significance of changes	Clause	Type		
		Minor and editorial changes	Extension	Major technical changes
Clarified that the track under component reduction factor only applies if the portion of the track underneath the component is greater than 10 mm.	5.4.4		X	
Use of the 1,3 W limit for thermal ignition compliance for Group III extended to include Group I.	5.4.5		X	
Board thickness, copper thickness and ambient temperature factors extended in use of Table 4.	5.4.4		X	
Enclosure requirement for Groups IIIA and IIIB aligned with Group I and Group II.	6.2.1		X	
Clarification that the IEC 60079-0 enclosure requirements apply for Group IIIC equipment with separations according to Table 7 (Ed 6 Table 5) that are reliant on an enclosure providing IP5X.	6.2.4 a)1)			C1
Requirement for a Specific Condition of Use added when use of reduced separations is reliant on an enclosure providing IP54.	6.2.5.1			C8
Plugs and sockets can comply with reduced separation requirements.	6.3.3		X	
Use of an enclosure to protect battery charging connections from spark ignition (Ed.6 clause 7.4.9) extended to include all non-hazardous area connection facilities.	6.3.5.2		X	
It is no longer necessary to define U_m for the connection from non-hazardous area connection facilities to accessories listed in the certificate provided the accessory is suitably marked and listed in the instructions.	6.3.5.3 11.1.5 12.1 j)		X	
It is no longer necessary to assess a non-hazardous area accessory in accordance with this standard.	6.3.5.3		X	
Clarification that charging of cells and batteries in the non-hazardous area has to be within the limits specified by their manufacturer, and IEC 60079-0.	6.3.5.3	X		
Conductors, connectors and PCB tracks have to be suitably rated for their failure to be a countable fault.	6.4.1			C9
It is now a stated requirement that circuits remain intrinsically safe after disconnection of a connector.	6.4.1			C1
It is now a requirement that infallible connections remain capable of carrying the current following considered fault disconnections.	6.4.2.2 6.4.2.3			C10
Infallible PCB connection achieved with two 1 mm wide tracks now have copper thickness requirements.	6.4.2.4			C11
The options for infallible PCB connections have been extended.	6.4.2.4		B2	
Clarification that connections complying with IEC 60079-7 Level of Protection "eb" can be considered infallible.	6.4.2.5	X		
Clarification that insulation of component packaging cannot be relied upon for separation of conductive parts unless it is specified by the component manufacturer, except for shorts to its solder pads where they are similar to the recommendations of the component manufacturer.	6.5.1	X		
Alternate spacing requirements from the previous edition Annex F have been transferred to the main body of this document.		A2		
Specific Condition of Use only required for Overvoltage Category (OVC) I/II when using Table 8 – Reduced separations.	6.5.3.2		X	
Dielectric strength requirements have been clarified in Table 8 – Reduced separations.	6.5.3.2			C12